

MOSFET – N-Channel, Shielded Gate, POWERTRENCH®

100 V, 47 A, 12.8 mΩ

FDMC86183

General Description

This N-Channel MV MOSFET is produced using onsemi's advanced POWERTRENCH process that incorporates Shielded Gate technology. This process has been optimized to minimise on-state resistance and yet maintain superior switching performance with best in class soft body diode.

Features

- Shielded Gate MOSFET Technology
- Max $R_{DS(on)}$ = 12.8 mΩ at $V_{GS} = 10$ V, $I_D = 16$ A
- Max $R_{DS(on)}$ = 34.6 mΩ at $V_{GS} = 6$ V, $I_D = 8$ A
- 50% Lower Q_{rr} than Other MOSFET Suppliers
- Lowers Switching Noise/EMI
- MSL1 Robust Package Design
- 100% UIL Tested
- Pb-Free, Halide Free and RoHS Compliant

Applications

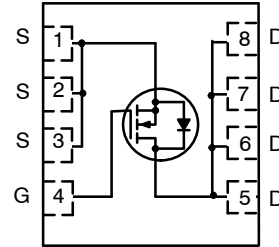
- Primary DC-DC MOSFET
- Synchronous Rectifier in DC-DC and AC-DC
- Motor Drive
- Solar

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

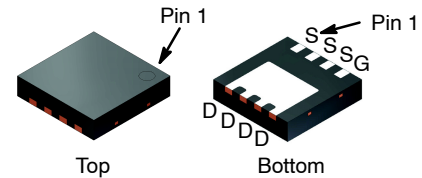
Symbol	Parameter	Value	Unit
V_{DS}	Drain to Source Voltage	100	V
V_{GS}	Gate to Source Voltage	±20	V
I_D	Drain Current: Continuous, $T_C = 25^\circ\text{C}$ (Note 5) Continuous, $T_C = 100^\circ\text{C}$ (Note 5) Continuous, $T_A = 25^\circ\text{C}$ (Note 1a) Pulsed (Note 4)	47 29 9.7 189	A
E_{AS}	Single Pulse Avalanche Energy (Note 3)	96	mJ
P_D	Power Dissipation: $T_C = 25^\circ\text{C}$ $T_A = 25^\circ\text{C}$ (Note 1a)	52 2.3	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

V_{DS}	$R_{DS(on)}$ MAX	I_D MAX
100 V	12.8 mΩ @ 10 V	47 A
	34.6 mΩ @ 6 V	

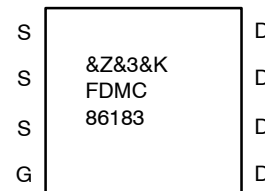


N-CHANNEL MOSFET



PQFN8 3.3 × 3.3, 0.65P
(Power 33)
CASE 483AX

MARKING DIAGRAM



&Z = Assembly Plant Code
&3 = Numeric Date Code
&K = Lot Code
FDMC86183 = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping†
FDMC86183	PQFN8 (Pb-Free, Halide Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	53	

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}$	100	–	–	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, referenced to 25°C	–	63	–	mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80 \text{V}, V_{GS} = 0 \text{V}$	–	–	1	μA
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{V}, V_{DS} = 0 \text{V}$	–	–	100	nA

ON CHARACTERISTICS

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 90 \mu\text{A}$	2.0	3.2	4.0	V
$\Delta V_{GS(th)} / \Delta T_J$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 90 \mu\text{A}$, referenced to 25°C	–	–8	–	mV/°C
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{V}, I_D = 16 \text{A}$	–	11	12.8	m Ω
		$V_{GS} = 6 \text{V}, I_D = 8 \text{A}$	–	18	34.6	
		$V_{GS} = 10 \text{V}, I_D = 16 \text{A}, T_J = 125^\circ\text{C}$	–	18	21	
g_{FS}	Forward Transconductance	$V_{DS} = 5 \text{V}, I_D = 16 \text{A}$	–	20	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 50 \text{V}, V_{GS} = 0 \text{V}, f = 1 \text{MHz}$	–	1080	1515	pF
C_{oss}	Output Capacitance		–	646	905	pF
C_{rss}	Reverse Transfer Capacitance		–	10	15	pF
R_g	Gate Resistance		0.1	0.5	1.5	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 50 \text{V}, I_D = 16 \text{A}, V_{GS} = 10 \text{V}, R_{GEN} = 6 \Omega$	–	11	20	ns
t_r	Rise Time		–	3	10	ns
$t_{d(off)}$	Turn-Off Delay Time		–	15	27	ns
t_f	Fall Time		–	3	10	ns
Q_g	Total Gate Charge	$V_{GS} = 0 \text{V to } 10 \text{V}, V_{DD} = 50 \text{V}, I_D = 16 \text{A}$	–	15	21	nC
		$V_{GS} = 0 \text{V to } 6 \text{V}, V_{DD} = 50 \text{V}, I_D = 16 \text{A}$	–	10	14	nC
Q_{gs}	Gate to Source Charge	$V_{DD} = 50 \text{V}, I_D = 16 \text{A}$	–	5	–	nC
Q_{gd}	Gate to Drain "Miller" Charge	$V_{DD} = 50 \text{V}, I_D = 16 \text{A}$	–	3.4	–	nC
Q_{oss}	Output Charge	$V_{DD} = 50 \text{V}, V_{GS} = 0 \text{V}$	–	43	–	nC

FDMC86183

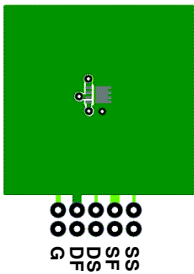
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted) (continued)

Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2.1 A (Note 2)	-	0.7	1.2	V
		V _{GS} = 0 V, I _S = 16 A (Note 2)	-	0.9	1.3	
t _{rr}	Reverse Recovery Time	I _F = 8 A, di/dt = 300 A/μs	-	22	36	ns
Q _{rr}	Reverse Recovery Charge		-	36	58	nC
t _{rr}	Reverse Recovery Time	I _F = 8 A, di/dt = 1000 A/μs	-	18	33	ns
Q _{rr}	Reverse Recovery Charge		-	79	127	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

- R_{θJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 × 1.5 in. board of FR-4 material. R_{θCA} is determined by the user's board design.



a) 53°C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125°C/W when mounted on a minimum pad of 2 oz copper.

- Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.
- E_{AS} of 96 mJ is based on starting T_J = 25°C; N-ch: L = 3 mH, I_{AS} = 8 A, V_{DD} = 100 V, V_{GS} = 10 V. 100% test at L = 0.3 mH, I_{AS} = 18 A.
- Pulsed I_d please refer to Figure 11 SOA graph for more details.
- Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

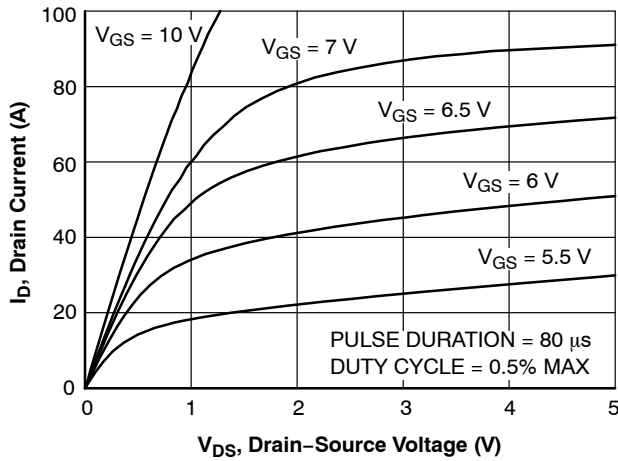


Figure 1. On-Region Characteristics

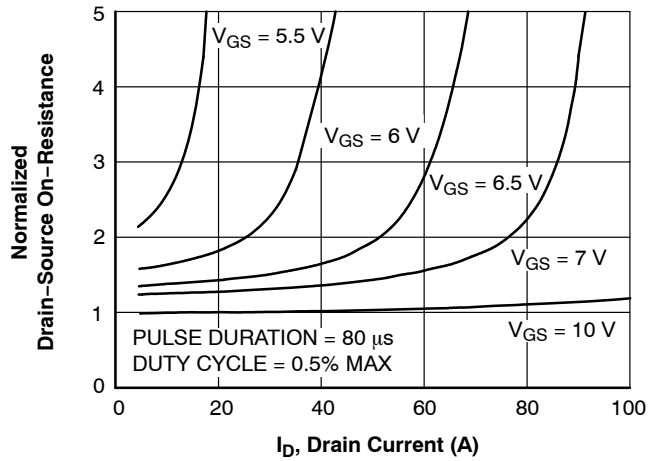


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

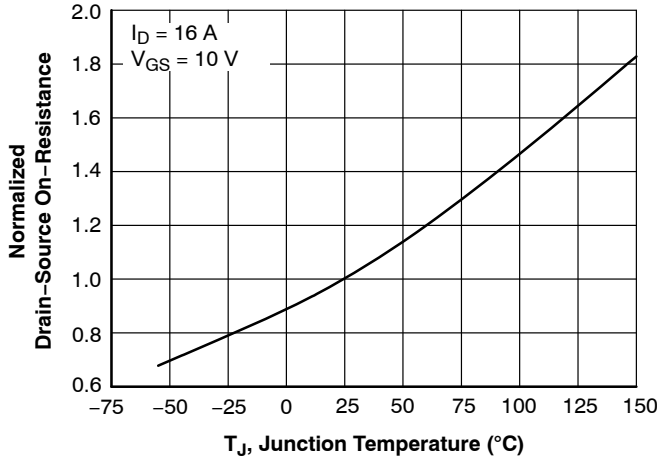


Figure 3. Normalized On-Resistance vs. Junction Temperature

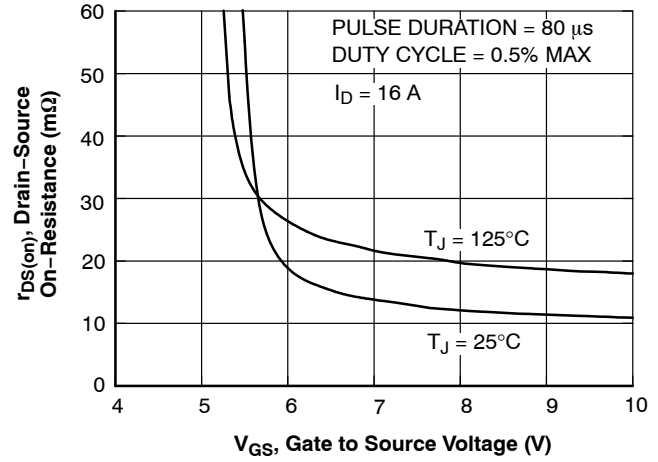


Figure 4. On-Resistance vs. Gate to Source Voltage

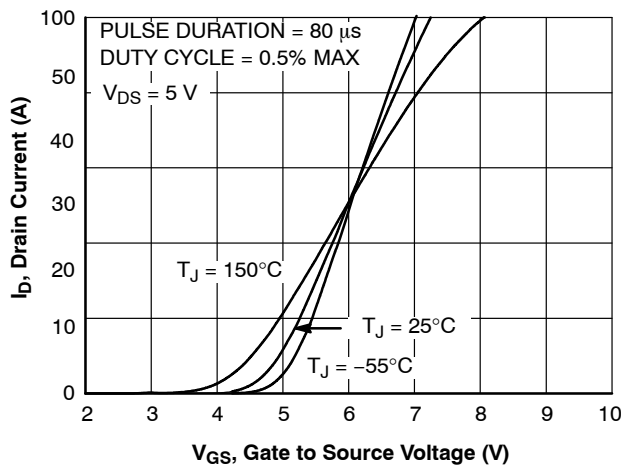


Figure 5. Transfer Characteristics

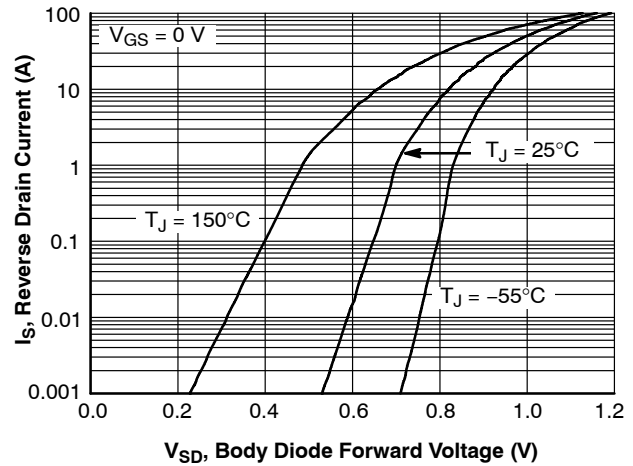


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

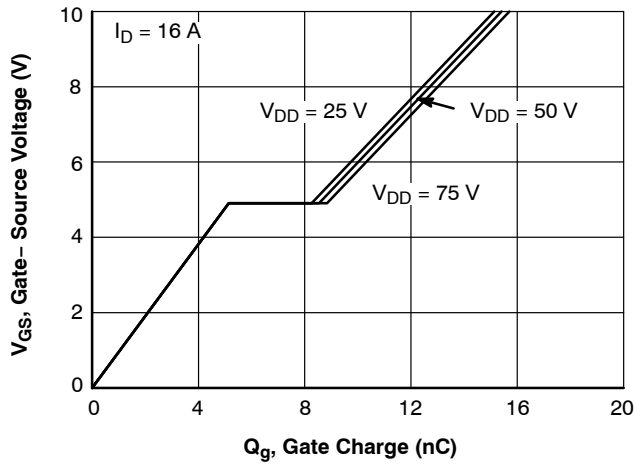


Figure 7. Gate Charge Characteristics

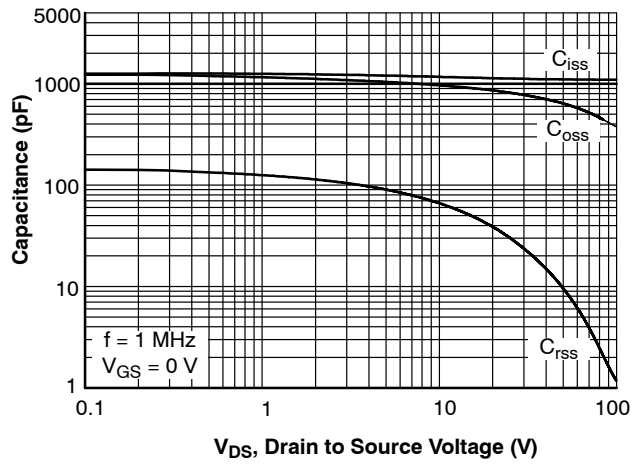


Figure 8. Capacitance vs. Drain to Source Voltage

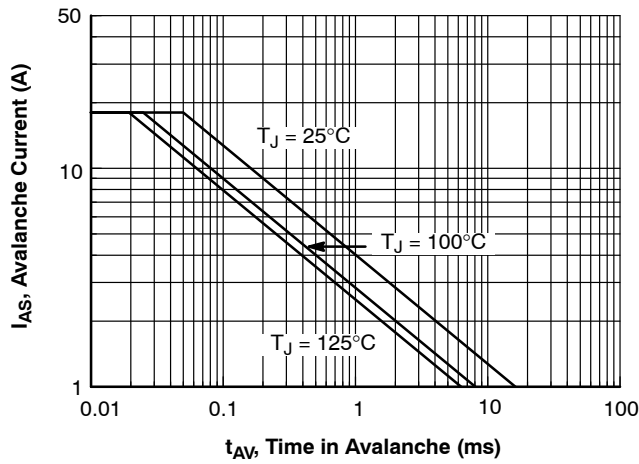


Figure 9. Unclamped Inductive Switching Capability

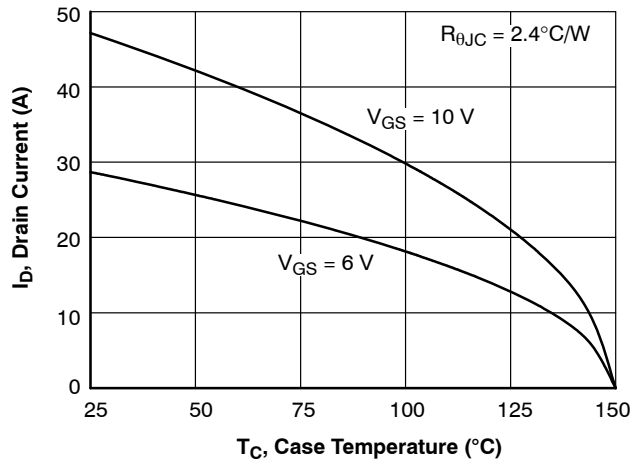


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

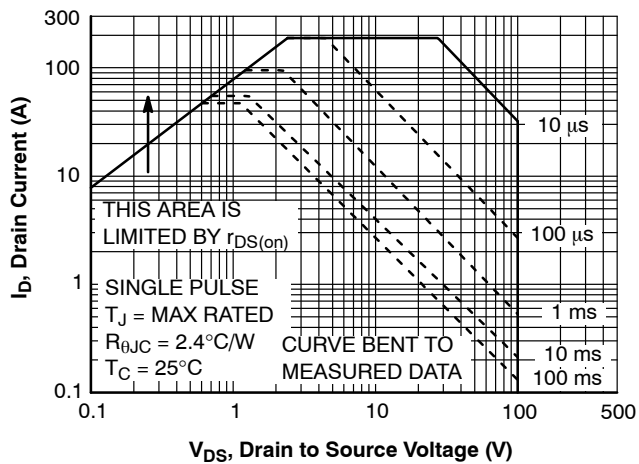


Figure 11. Forward Bias Safe Operating Area

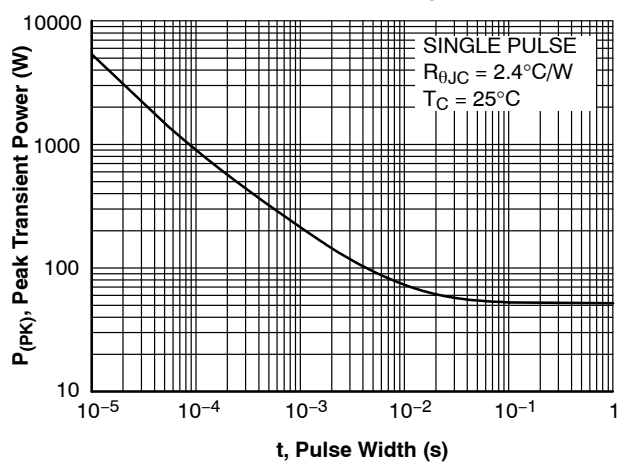


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

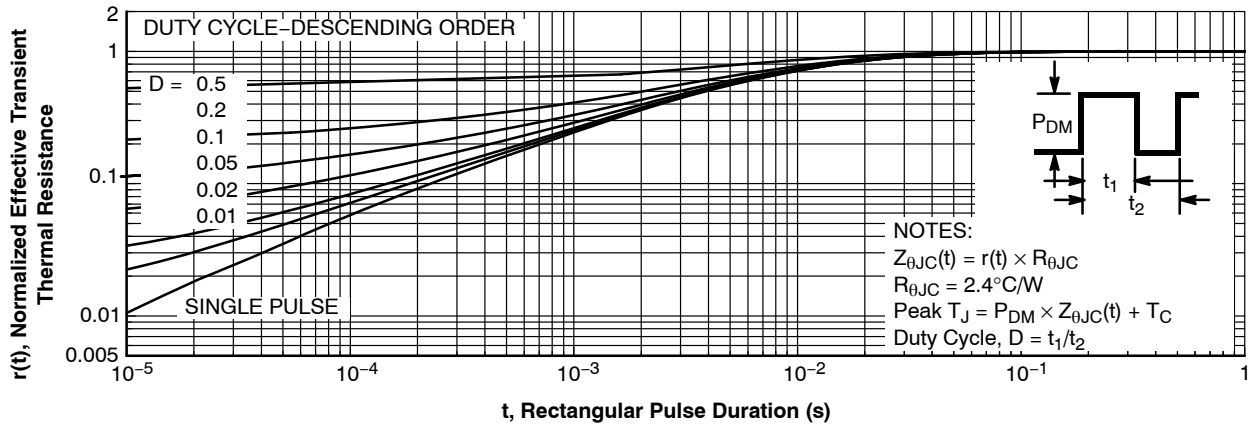
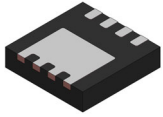


Figure 13. Junction-to-Case Transient Thermal Response Curve

MECHANICAL CASE OUTLINE

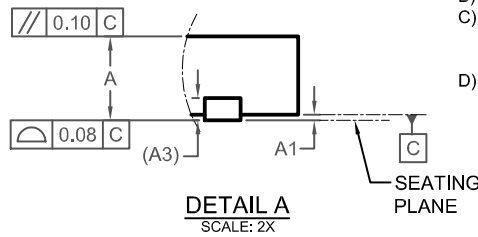
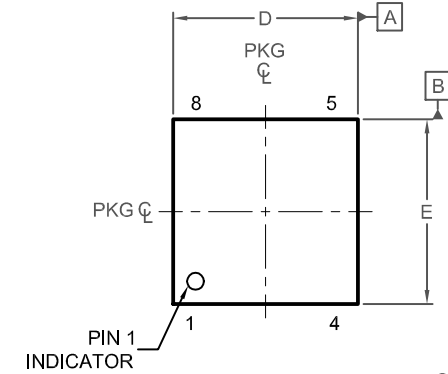
PACKAGE DIMENSIONS

ON Semiconductor®



PQFN8 3.3X3.3, 0.65P
CASE 483AX
ISSUE B

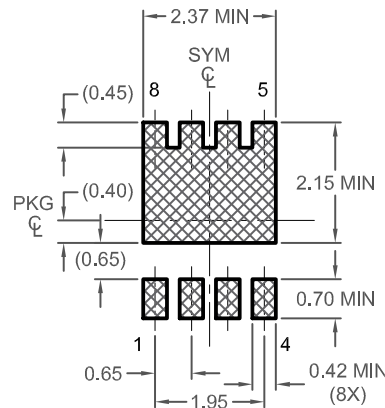
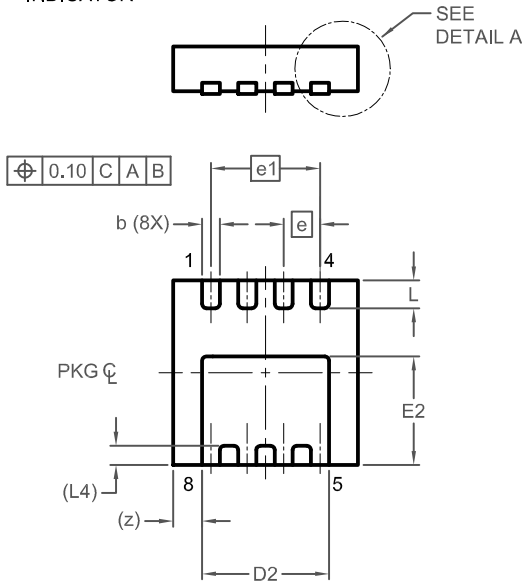
DATE 24 JUN 2022



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	-	0.05
A3	0.20 REF		
b	0.27	0.32	0.37
D	3.20	3.30	3.40
D2	2.17	2.27	2.37
E	3.20	3.30	3.40
E2	1.84	1.94	2.04
e	0.65 BSC		
e1	1.95 BSC		
L	0.40	0.50	0.60
L4	0.34 REF		
z	0.52 REF		



LAND PATTERN RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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